

CLAIMS

What is claimed is:

1. A hermetic seal for an electronic circuit die comprising:

5 an inorganic layer for preventing moisture from reaching the electronic circuit die; and
 an organic layer outside the inorganic layer for protecting the inorganic layer.

10 2. The apparatus of claim 1 wherein the inorganic layer is adjacent to the organic layer.

15 3. The apparatus of claim 1 further comprising a plastic package.

15 4. The apparatus of claim 3 wherein the inorganic layer is outside the plastic package.

20 5. The apparatus of claim 4 wherein the inorganic layer is inside the plastic package.

20 6. The apparatus of claim 1 further comprising:
 a lead; and
 a wire;

wherein the inorganic layer contacts the lead.

7. The apparatus of claim 1 wherein the
inorganic layer comprises a material selected from the
5 group consisting of metal oxides, silicon nitride, silicon
carbide, aluminum nitride, and diamond-like carbons.

8. The apparatus of claim 1 wherein the organic
layer comprises a material consisting of para-xylyene,
10 hybrid solgel, and polymeric materials.

9. A method of making a hermetic seal
comprising:

providing an inorganic layer for protecting from
15 moisture; and

providing an organic layer for protecting the
inorganic layer.

10. The method of claim 9 further comprising:

20 providing a lead, wherein the lead contacts the
inorganic material.

11. The method of claim 9 further comprising
providing a plastic package.

12. The method of claim 11, wherein the plastic package contacts the inorganic layer.

5 13. The method of claim 11, wherein the plastic package contacts the organic layer.

10 14. A hermetically sealed device comprising:
an electronic circuit die;
an inorganic layer outside the electronic circuit
die; and
an organic layer outside the inorganic material.

15 15. The hermetically sealed device of claim 14
further comprising:
a wire; and
a lead;
wherein the inorganic layer contacts the lead.

20 16. The hermetically sealed device of claim 14
wherein the inorganic layer comprises a material selected
from the group consisting of metal oxides, silicon nitride,
silicon carbide, aluminum nitride, and diamond-like
carbons.

17. The hermetically sealed device of claim 14
wherein the organic layer comprises a material consisting
of para-xylyene, hybrid solgel, and polymeric materials.

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18. The hermetically sealed device of claim 14
further comprising:

a wire;
a lead; and
10 a plastic package.

19. The hermetically sealed device of claim 18
wherein the plastic package contacts the inorganic layer.

15 20. The hermetically sealed device of claim 18
wherein the plastic package contacts the organic layer.

21. The hermetically sealed device of claim 14
wherein the inorganic layer encloses the electronic circuit
20 die.